



08-17-2001



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document or copy thereof.

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1. Name of party or parties conveying an interest: Jin Seok Kim Sang Ho Han Sung Gyu Pyo Si Bum Kim	2. Name and address of party or parties receiving an interest: Name: Hyundai Electronics Industries Co. Address: San 136-1, Ami-Ri Bubal-Uep, Ichon-Shi Kyungki-Do Republic of KOREA
3. Description of the interest conveyed: <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Change of Name <input type="checkbox"/> Security Agreement Execution Date: April 18, 2001	Other: 406
4. Application number(s) or patent number(s). Additional sheet attached? YES <input type="checkbox"/> NO <input checked="" type="checkbox"/>	If the document is being filed together with a new application, the execution date of the application is:
A. Patent Application no.(s): 09/875,625 filed June 6, 2001	B. Patent no.(s):
5. Name and address of party to whom correspondence concerning this cover sheet should be mailed: Name: James A. Flight Reg. No. 37,622 MARSHALL, GERSTEIN & BORUN Street Address: 6300 Sears Tower 233 S. Wacker Drive City: Chicago State: Illinois Zip: 60606-6402	6. Number of applications and/or patents identified on this cover sheet: 1 7. Amount of fee enclosed or authorized to be charged: \$40.00 8. Any additional required fee may be charged, or any overpayment credited to our deposit account: 13-2855

9. To the best of my knowledge and belief, the information contained on this cover sheet is true and correct and any copy submitted is a true copy of the original document.

Date: 8/11/01

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James A. Flight
Reg. No. 37,622

Total number of pages including cover sheet, attachments, and document: 2

PATENT
REEL: 012070 FRAME: 0701

A S S I G N M E N TSerial No: 09/875,625Filed: June 6, 2001Title: METHOD OF MANUFACTURING A COPPER METAL WIRING IN A SEMICONDUCTOR DEVICE

For good and valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assign(s) to HYUNDAI ELECTRONICS INDUSTRIES CO., LTD. of San 136-1, Ami-Ri, Bubal-Uep, Ichon-Shi, Kyungki-Do, Republic of Korea, (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, executed by the undersigned on April 18, 2001, and in said application and any and all other applications, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States, which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

The undersigned hereby authorize(s) and request(s) the attorneys of record in said application to insert in this assignment the execution date and/or filing date and serial number of said application when officially known.

The undersigned warrant(s) themselves (himself/herself) to be the owners (owner) of the interest herein assigned and to have the right to make this assignment and further warrant(s) that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned.

For said consideration the undersigned hereby agree(s), upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation, continuation-in-part and substitute applications for said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application, that said assignee, its successors or assigns, may deem necessary or expedient, and for the aforesaid consideration the undersigned further agree(s) upon the request of said assignee, its successors or assigns, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned with said assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said Letters Patent, and vest all rights therein hereby conveyed in said assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by said assignee, its successors and assigns, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

WITNESS my (our) hand(s) this 18 day of April, 2001.

Witnesses:

1) Jin Seok Kim
Name: Jin Seok KIM

2) Sang Ho Han
Name: Sang Ho HAN

1. Sung Gyu Pyo
Inventor: Sung Gyu PYO

2. Si Bum Kim
Inventor: Si Bum KIM